

5G WIRELESS MODULE TEARDOWN REPORTS: Huawei MH5000-31; Quectel RM500Q-GL; Sierra Wireless AirPrime EM9190



Huawei MH5000-31



Quectel RM500Q-GL



Sierra Wireless AirPrime EM9190

Product overview

Huawei MH5000-31 :This is the first 5G module for automobiles application by Huawei announced in April 2019. They also announced that this is the high-speed, high-quality 5G communication hardware, delivering to automobile makers in the second half of 2019.

CPU: HiSilicon 5G multi-mode terminal chip "Balong 5000"

Quectel RM500Q-GL: Quectel is the world's No. 1 module vendor for LTE module. They released 5G module in July 2020. This product is for IoT/eMBB (Enhanced Mobile BroadBand) 5G communication hardware.

CPU: Qualcomm Snapdragon X55 5G Modem

Sierra Wireless AirPrime EM9190): This product was released in July 2020. It is for 5G communication for IoT/eMBB (Enhanced Mobile BroadBand) hardware

CPU: Qualcomm Snapdragon X55 5G Modem

Report content

The simple teardown report includes teardown process images, X-ray, identifying key semiconductors and number of components including passive components.

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